

CLAIMS

We claim:

- 1 1. A method for attaching a module to a printed circuit board comprising
2 the steps of:
3 attaching a standoff to the module;
4 applying a ball grid array to the module;
5 positioning the module such that the standoff is between the printed
6 circuit board and the module; and
7 reflowing the ball grid array.

- 1 2. An electrical attachment comprising:
2 a module having connection pads on a bottom surface;
3 a standoff, positioned on the bottom surface, having a height;
4 a printed circuit board having connection pads;
5 a ball grid array, interposing the connection pads of the module and the
6 printed circuit board, wherein the height of the ball grid array is comparable to
7 the height of the standoff. (US 5, 200, 000 2b)

- 1 3. An electrical attachment, as defined in claim 2, wherein the standoff is
2 an insulative material.

- 1 4. An electrical attachment, as defined in claim 3, wherein the insulative
2 material is silicon.

- 1 5. An electrical attachment, as defined in claim 2, further comprising a
2 flexible circuit interposing the module and the standoff.

- 1 6. An electrical attachment, as defined in claim 5, wherein the standoff is
2 an insulative material.

- 1 7. An electrical attachment, as defined in claim 6, wherein the insulative
2 material is silicon.